



产品编号 : 855035001

Product Description : Modular Jack, Cat5e, Right-Angle, Through Hole, 8/8, Tray

系列号 : 85503

状态 : Active

Product Category : Modular Jacks and Plugs

文件和资源

图纸

图纸 855035001_sd.pdf

包装设计图 PK-95001-001.pdf

3D 模型和设计文件

3D模型 855035001_stp.zip


规格

应用规格 AS-85513-001-001.pdf

产品规格 PS-85503-001-001.pdf

产物环境合规

合规

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)8585-DC (23 Jan 2024)
EU RoHS	Compliant per EU 2015/863

多部分产品合规性声明

- Eu RoHS
- REACH SVHC
- Low-Halogen
- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

产品详情

常规

状态	活动
类别	Modular Jacks and Plugs
系列	85503
说明	Modular Jack, Cat5e, Right-Angle, Through Hole, 8/8, Tray
个评论	Reflow Capable
元件类型	PCB Jack
磁性的	否
性能分类	5e
以太网电源 (PoE)	不适用
产品系列	Magnetic and Modular Jacks/Plugs
产品名称	Modular Jack 8/8, RJ45
UPC	822350976619

机构

UL	E107635
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电气

每触点最大电流	1.5A
屏蔽	否
电压 - 最大	125V DC

物理

衬套颜色	不适用
颜色-树脂	黑色
耐用性(插拔次数) - 最多次数	2500
阻燃性	94V-0
向下 / 向上锁闩	否
插孔高度	11.50mm
光管/发光二极管	无
材料 - 金属	Phosphor Bronze

材料 - 接合部位电镀	Gold over Palladium Nickel
材料 - 终端电镀	Tin
材料 - 树脂	High Temperature Thermoplastic
净重	2.300/g
方向	Right Angle (Side Entry)
包装形式	Tray
PCB 定位器	是
PCB 保持力	是
推荐的 PCB 厚度	1.57mm
间距 - 插配接口	1.02mm
间距 - 终端界面	1.27mm
最薄镀层 - 接合部位	0.051 μ m, 0.600 μ m
最薄镀层 - 端接	1.905 μ m
端口配置	1x1
位置/插入的接头	8/8
运行温度范围	-40° to +85° C
终端界面类型	Through Hole
防水/防尘	否
导线/电缆型号	不适用

进程

最长持续时间	5
无铅	WAVE
最大周期	1
最高温度	260

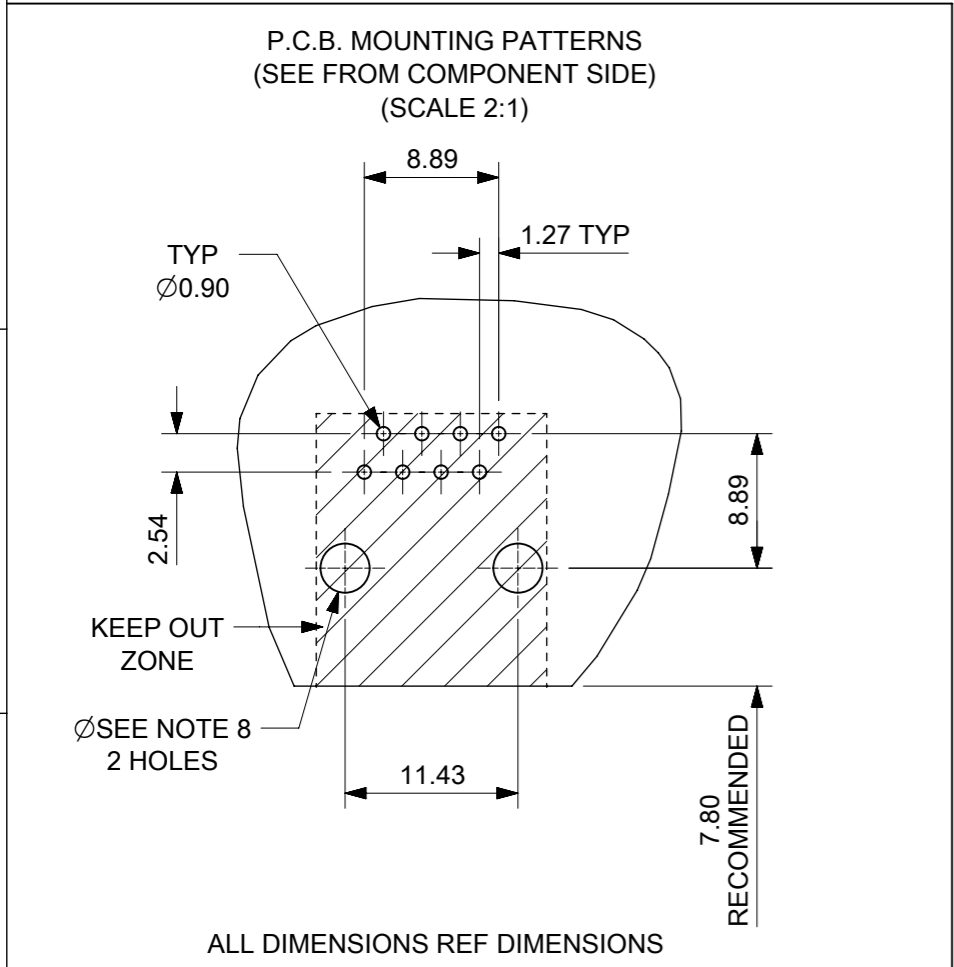
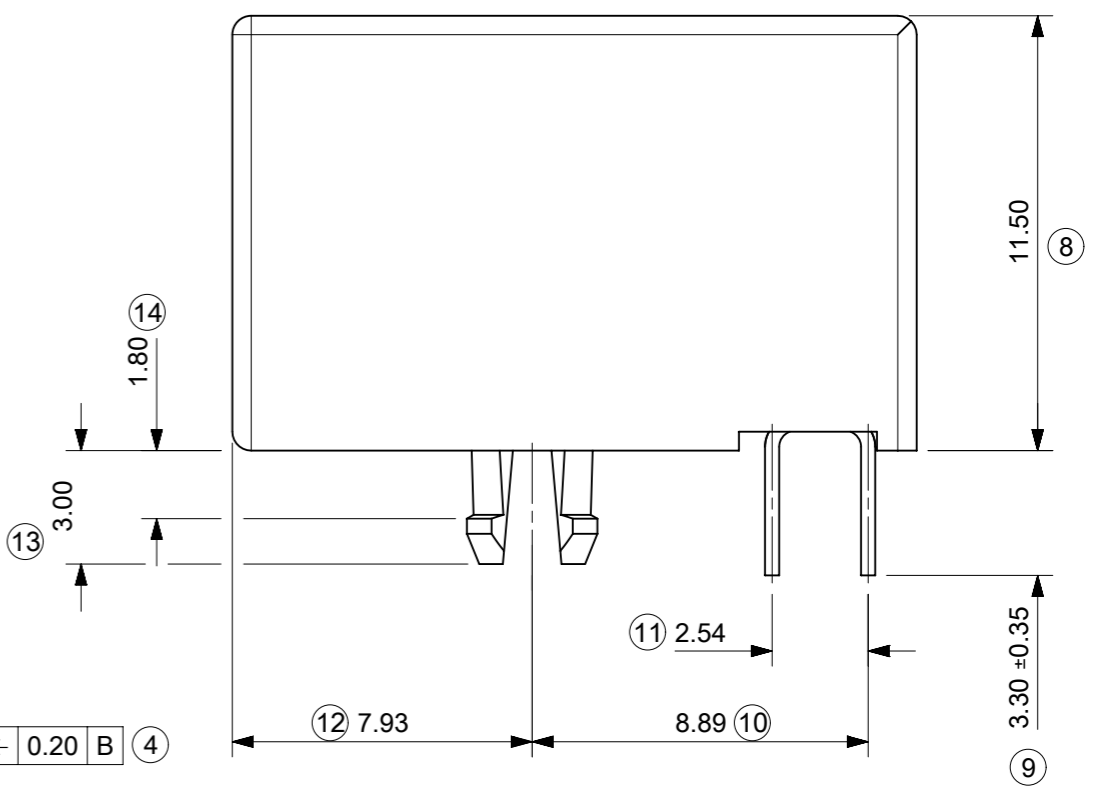
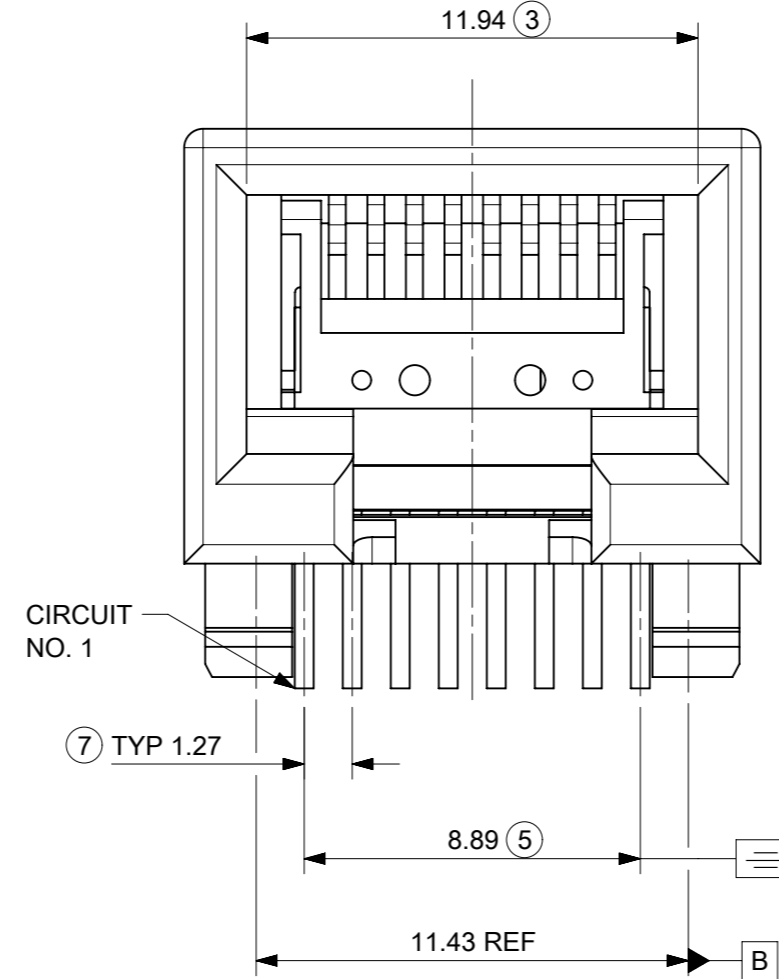
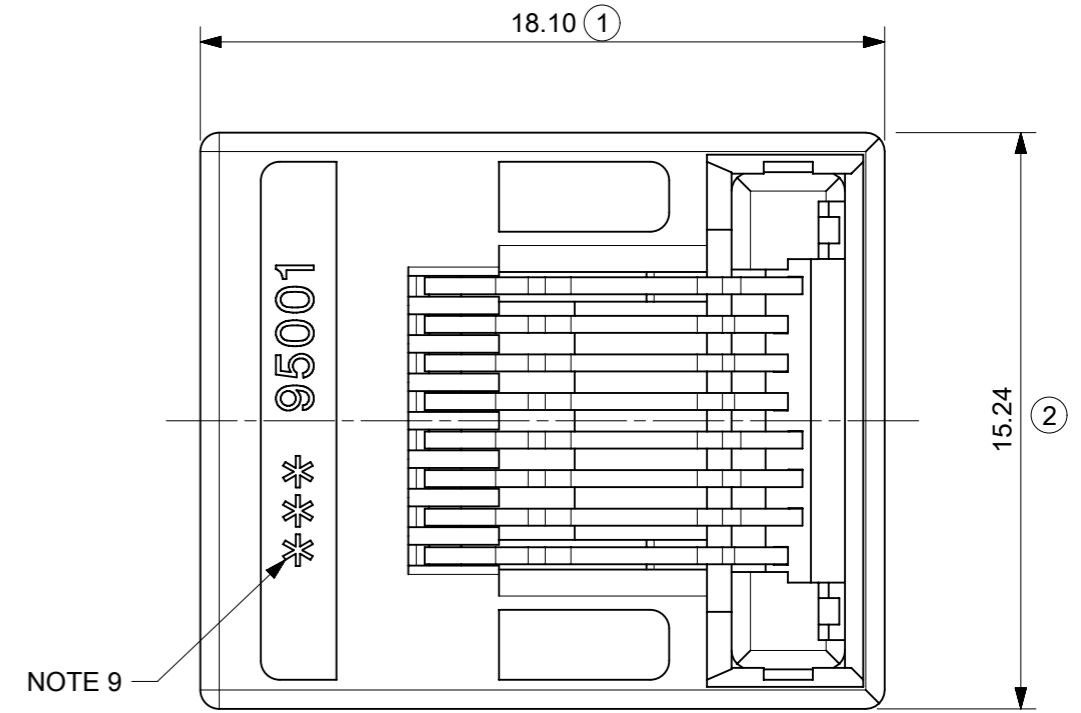
NOTES:

1. **MATERIAL:**
 HOUSING: LCP FIBER GLASS FILLED UL 94-V0, COLOUR: BLACK
 TERMINAL: PHOSPHOR BRONZE.
 BASE FINISH: NICKEL
 CONTACT SURFACE FINISH:
 GOLD
 OR
 GOLD FLASH OVER PALLADIUM NICKEL.
 EXCEEDS PRODUCT REQUIREMENTS BASED ON PS-85503-001

2. JACK FOR MATING WITH F.C.C. 68 PLUGS (90075 MOLEX SERIES).
 3. PRODUCT SPECIFICATION: PS-85503-001.
 4. APPLICATION SPECIFICATION AS-85513-001
 5. PACKAGING SPECIFICATION: PK-95001: STANDARD PACKAGING SHEET 1.
 6. EXCEEDS CATEGORY 5E PERFORMANCE.
 7. P.C. BOARD THICKNESS: 1.57
 8. CONVECTION SOLDERING DIA 3.25±0.05.
 WAVE SOLDERING DIA 3.2±0.1
 9. MANUFACTURING I.D. CAN BE EITHER MXF MG MXI OR MXCH.

LAST INSPECTION NO.: 14
 REMOVED INSPECTION NO.: 6

MATERIAL NO.
85503-5001



THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC:		molex	
DIMENSION UNITS	SCALE	EC NO: 686812			
mm	5:1	DRWN: DBYRNES 2021/11/10		RIGHT ANGLE LOW PROFILE THROUGH HOLE 8	
GENERAL TOLERANCES (UNLESS SPECIFIED)		CHK'D: KLANG 2022/01/11		CIRCUIT	
ANGULAR TOL	± 0.5°	APPR: KLANG 2022/01/11		PRODUCT CUSTOMER DRAWING	
4 PLACES	±	INITIAL REVISION:		DOCUMENT NUMBER	DOC TYPE
3 PLACES	±	DRWN: TMARTIN 2005/03/22		SD-85503-101	PSD
2 PLACES	± 0.15	APPR: KNOLLER 2005/04/04		001	C2
1 PLACE	± 0.25			MATERIAL NUMBER	CUSTOMER
0 PLACES	±			SEE TABLE	GENERAL MARKET
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	SHEET NUMBER
			A3-SIZE	85503	1 OF 1

DOCUMENT STATUS	P1	RELEASE DATE	2022/01/11	16:13:44
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